HARRIS SEMICONDUCTOR

HC-5509B

SLIC
Subscriber Line Interface Circuit

September 1995

Features

- DI Monolithic High Voltage Process
- Compatible with Worldwide PBX and CO Performance Requirements
- Controlled Supply of Battery Feed Current with Programmable Current Limit
- Operates with 5V Positive Supply (V_{B+})
- Internal Ring Relay Driver and a Utility Relay Driver
- High Impedance Mode for Subscriber Loop
- High Temperature Alarm Output
- Low Power Consumption During Standby Functions
- Switch Hook, Ground Key, and Ring Trip Detection
- Selective Power Denial to Subscriber
- Voice Path Active During Power Denial
- On-Chip Op Amp for 2-Wire Impedance Matching

Applications

- Solid State Line Interface Circuit for PBX or Central Office Systems, Digital Loop Carrier Systems
- Hotel/Motel Switching Systems
- Direct Inward Dialing (DID) Trunks
- Voice Messaging PBXs
- High Voltage 2-Wire/4-Wire, 4-Wire/2-Wire Hybrid

Ordering Information

PART NUMBER	TEMP. RANGE	PACKAGE
HC1-5509B-5	0° to +75°C	28 Lead CerDIP
HC1-5509B-9	-40° to +85°C	28 Lead CerDIP
HC3-5509B-5	0° to +75°C	28 Lead Plastic DIP
HC3-5509B-9	-40° to +85°C	28 Lead Plastic DIP
HC4P5509B-5	0° to +75°C	44 Lead PLCC
HC4P5509B-9	-40° to +85°C	44 Lead PLCC
HC9P5509B-5	0° to +75°C	28 Lead Plastic SOIC
HC9P5509B-9	-40° to +85°C	28 Lead Plastic SOIC

Description

The HC-5509B telephone Subscriber Line Interface Circuit integrates most of the BORSCHT functions on a monolithic IC. The device is manufactured in a Dielectric Isolation (DI) process and is designed for use as a high voltage interface between the traditional telephone subscriber pair (Tip and Ring) and the low voltage filtering and coding/decoding functions of the line card. Together with a secondary protection diode bridge and "feed" resistors, the device will withstand 1000V lightning induced surges, in plastic packages. The SLIC also maintains specified transmission performance in the presence of externally induced longitudinal currents. The BORSCHT functions that the SLIC provides are:

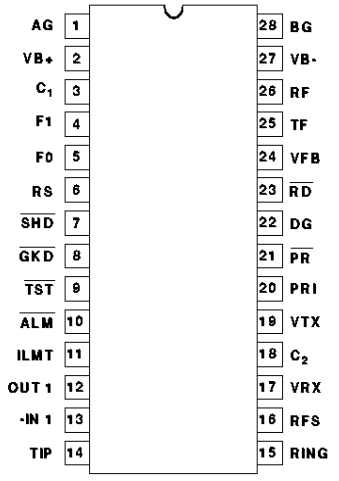
- Battery Feed with Subscriber Loop Current Limiting
- Overvoltage Protection
- Ring Relay Driver
- Supervisory Signaling Functions
- Hybrid Functions (with External Op-Amp)
- Test (or Battery Reversal) Relay Driver

In addition, the SLIC provides selective denial of power to subscriber loops, a programmable subscriber loop current limit from 20mA to 60mA, a thermal shutdown with an alarm output and line fault protection. Switch hook detection, ring trip detection and ground key detection functions are also incorporated in the SLIC device.

The HC-5509B SLIC is ideally suited for line card designs in PBX and CO systems, replacing traditional transformer solutions.

Pinouts

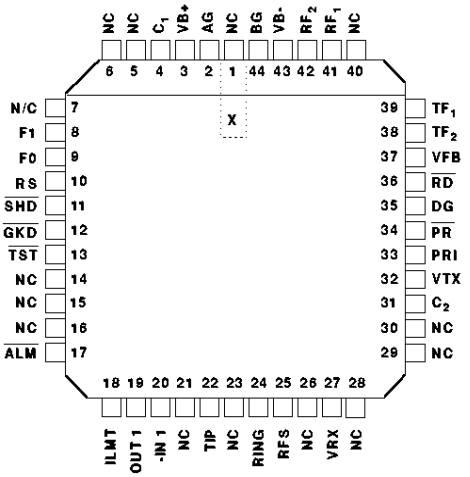
HC-5509B (PDIP, CERDIP, SOIC)
TOP VIEW



TRUTH TABLE

F1	F0	ACTION
0	0	Normal Loop Feed
0	1	$\overline{RD}$ Active
1	0	Power Down Latch RESET
1	0	Power on RESET
1	1	Loop Power Denial Active

HC-5509B (PLCC)
TOP VIEW



CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

File Number **2799.3**

Absolute Maximum Ratings (Note 1)

Relay Drivers . . . . . -0.5V to +15V
Maximum Supply Voltages
(V_{B+}) . . . . . -0.5V to +7V
(V_{B+})-(V_{B-}) . . . . . +75V
Junction Temperature Ceramic . . . . . +175°C
Junction Temperature Plastic . . . . . +150°C
Lead Temperature (Soldering 10s) . . . . . +300°C
(For SMD; PLCC and SOIC - Lead Tips Only)

Operating Conditions

Operating Temperature Range
HC-5509B-5 . . . . . 0°C to +75°C
HC-5509B-9 . . . . . -40°C to +85°C
Storage Temperature Range . . . . . -65°C to +150°C
Relay Drivers . . . . . +5V to +12V
Positive Power Supply (V_{B+}) . . . . . +5V ±5%
Negative Power Supply (V_{B-}) . . . . . -42V to -58V
Loop Resistance (R_L) . . . . . 200Ω to 1750Ω (Note 2)

Thermal Information

Thermal Resistance (Typical)	θ_{JA}	θ_{JC}
CerDIP Package	48°C/W	12°C/W
Plastic DIP Package	51°C/W	N/A
PLCC Package	47°C/W	N/A
SOIC Package	72°C/W	N/A

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Specifications Unless Otherwise Specified, Typical Parameters are at T_A = +25°C, Min-Max Parameters are Over Operating Temperature Range, V_{B-} = -48V, V_{B+} = +5V, AG = DG = BG = 0V. All AC Parameters are specified at 600Ω 2-Wire Terminating Impedance.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
AC TRANSMISSION PARAMETERS					
RX Input Impedance	300Hz to 3.4kHz (Note 3)	-	100	-	kΩ
TX Output Impedance	300Hz to 3.4kHz (Note 3)	-	-	20	Ω
4-Wire Input Overload Level	300Hz to 3.4kHz R_L = 1200Ω, 600Ω Reference	+1.5	-	-	V_{PEAK}
2-Wire Return Loss	Matched for 600Ω (Note 3)				
SRL LO		26	35	-	dB
ERL		30	40	-	dB
SRL HI		30	40	-	dB
2-Wire Longitudinal to Metallic Balance Off Hook	Per ANSI/IEEE STD 455-1976 (Note 3) 300Hz to 3400Hz	58	63	-	dB
4-Wire Longitudinal Balance Off Hook	300Hz to 3400Hz (Note 3)	50	55	-	dB
Low Frequency Longitudinal Balance	R.E.A. Test Circuit	-	-	-67	dBmp
	I_{LINE} = 40mA T_A = +25°C (Note 3)	-	-	23	dBrnC
Longitudinal Current Capability	I_{LINE} = 40mA T_A = +25°C (Note 3)	-	-	30	mA_{RMS}
Insertion Loss	0dBm at 1kHz, Referenced 600Ω				
2-Wire/4-Wire		-	±0.05	±0.2	dB
4-Wire/2-Wire		-	±0.05	±0.2	dB
4-Wire/4-Wire		-	-	±0.2	dB
Frequency Response	300Hz to 3400Hz (Note 3) Referenced to Absolute Level at 1kHz, 0dBm Referenced 600Ω	-	±0.02	±0.05	dB
Level Linearity	Referenced to -10dBm (Note 3)				
2-Wire to 4-Wire and 4-Wire to 2-Wire	+3 to -40dBm	-	-	±0.05	dB
	-40 to -50dBm	-	-	±0.1	dB
	-50 to -55dBm	-	-	±0.3	dB

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PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Absolute Delay	(Note 3)				
2-Wire/4-Wire	300Hz to 3400Hz	-	-	1	µs
4-Wire/2-Wire	300Hz to 3400Hz	-	-	1	µs
4-Wire/4-Wire	300Hz to 3400Hz	-	-	1.5	µs
Transhybrid Loss, THL	(Note 3) See Figure 1	-	40	-	dB
Total Harmonic Distortion 2-Wire/4-Wire, 4-Wire/2-Wire, 4-Wire/4-Wire	Reference Level 0dBm at 600Ω 300Hz to 3400Hz (Note 3)	-	-	-52	dB
Idle Channel Noise	(Note 3)				
2-Wire and 4-Wire	C-Message	-	-	5	dBrnC
	Psophometric	-	-	-85	dBmp
	3kHz Flat	-	-	15	dBrn
Power Supply Rejection Ratio	(Note 3) 30Hz to 200Hz, R_L = 600Ω				
V_{B+} to 2-Wire		20	29	-	dB
V_{B+} to 4-Wire		20	29	-	dB
V_{B-} to 2-Wire		20	29	-	dB
V_{B-} to 4-Wire		20	29	-	dB
V_{B+} to 4-Wire	(Note 3) 200Hz to 16kHz, R_L = 600Ω	30	-	-	dB
V_{B-} to 2-Wire		30	-	-	dB
V_{B-} to 4-Wire		20	25	-	dB
V_{B-} to 4-Wire		20	25	-	dB
Ring Sync Pulse Width		50	-	500	µs
DC PARAMETERS					
Loop Current Programming					
Limit Range		20	40	60	mA
Accuracy		10	-	-	%
Loop Current During Power Denial	R_L = 200Ω	-	±3	±5	mA
Fault Currents					
TIP to Ground		-	30	-	mA
RING to Ground		-	60	-	mA
TIP and RING to Ground		-	90	-	mA
Switch Hook Detection Threshold		-	12	15	mA
Ground Key Detection Threshold		-	10	-	mA
Thermal $\overline{\text{ALARM}}$ Output	Safe Operating Die Temperature Exceeded	140	-	160	°C
Ring Trip Detection Threshold	V_{RING} = 105V_{RMS}, f_{RING} = 20Hz	-	10	-	mA
Ring Trip Detection Period		-	100	150	ms
Dial Pulse Distortion		-	0.1	0.5	ms

Electrical Specifications Unless Otherwise Specified, Typical Parameters are at T_A = +25°C, Min-Max Parameters are Over Operating Temperature Range, V_{B-} = -48V, V_{B+} = +5V, AG = DG = BG = 0V. All AC Parameters are specified at 600Ω 2-Wire Terminating Impedance. **(Continued)**

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Relay Driver Outputs					
On Voltage V_{OL}	I_{OL} ($\overline{PR}$) = 60mA, I_{OL} ($\overline{RD}$) = 30mA	-	0.2	0.5	V
Off Leakage Current	V_{OH} = 13.2V	-	±10	±100	µA
TTL/CMOS Logic Inputs (F0, F1, RS, $\overline{TEST}$, PRI)					
Logic '0' V_{IL}		-	-	0.8	V
Logic '1' V_{IH}		2.0	-	5.5	V
Input Current (F0, F1, RS, $\overline{TEST}$, PRI)	0V ≤ V_{IN} ≤ 5V	-	-	±100	µA
Logic Outputs					
Logic '0' V_{OL}	I_{LOAD} = 800µA	-	0.1	0.5	V
Logic '1' V_{OH}	I_{LOAD} = 40µA	2.7	-	-	V
Power Dissipation On Hook	Relay Drivers Off	-	200	-	mW
I_{B+}	V_{B+} = +5.25V, V_{B-} = -58V, R_{LOOP} = ∞	-	-	6	mA
I_{B-}	V_{B+} = +5.25V, V_{B-} = -58V, R_{LOOP} = ∞	-6	-	-	mA
UNCOMMITED OP AMP PARAMETERS					
Input Offset Voltage		-	±5	-	mV
Input Offset Current		-	±10	-	nA
Differential Input Resistance	(Note 3)	-	1	-	MΩ
Output Voltage Swing	R_L = 10kΩ	-	±3	-	V_{P-P}
Small Signal GBW	(Note 3)	-	1	-	MHz

NOTES:

1. Absolute maximum ratings are limiting values, applied individually, beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied.
2. May Be Extended to 1900Ω With Application Circuit.
3. These parameters are controlled by design or process parameters and are not directly tested. These parameters are characterized upon initial design release, upon design changes which would affect these characteristics, and at intervals to assure product quality and specification compliance.

Pin Descriptions

DIP/SOIC	PLCC	SYMBOL	DESCRIPTION
1	2	AG	Analog Ground - To be connected to zero potential. Serves as a reference for the transmit output and receive input terminals.
2	3	VB+	Positive Voltage Source - most positive supply.
3	4	C_1	Capacitor #C_1 - An external capacitor to be connected between this terminal and analog ground. Required for proper operation of the loop current limiting function.
4	8	F1	Function Address #1 - A TTL and CMOS compatible input used with F0 function address line to externally select logic functions. The three selectable functions are mutually exclusive. See Truth Table on page1. F1 should be toggled high after power is applied.
5	9	F0	Function Address #0 - A TTL and CMOS compatible input used with F1 function address line to externally select logic functions. The three selectable functions are mutually exclusive. See Truth Table on page 1.
6	10	RS	Ring Synchronization Input - A TTL - compatible clock input. The clock is arranged such that a positive pulse (50 - 500µs) occurs on the zero crossing of the ring voltage source, as it appears at the RFS terminal. For Tip side injected systems, the RS pulse should occur on the negative going zero crossing and for Ring injected systems, on the positive going zero crossing. This ensures that the ring delay activates and deactivates when the instantaneous ring voltage is near zero. If synchronization is not required, the pin should be tied to +5.
7	11	$\overline{SHD}$	Switch Hook Detection - An active low LS TTL compatible logic output. A line supervisory output.
8	12	$\overline{GKD}$	Ground Key Detection - An active low LS TTL compatible logic output. A line supervisory output.
9	13	$\overline{TST}$	A TTL logic input. A low on this pin will set a latch and keep the SLIC in a power down mode until the proper F1, F0 state is set and will keep $\overline{ALM}$ low. See Truth Table on page 1.
10	17	$\overline{ALM}$	A LS TTL compatible active low output which responds to the thermal detector circuit when a safe operating die temperature has been exceeded. When $\overline{TST}$ is forced low by an external control signal, $\overline{ALM}$ is latched low until the proper F1, F0 state and $\overline{TST}$ input is brought high. The $\overline{ALM}$ can be tied directly to the $\overline{TST}$ pin to power down the part when a thermal fault is detected and then reset with F0, F1. See Truth Table on page 1. It is possible to ignore transient thermal overload conditions in the SLIC by delaying the response to the $\overline{TST}$ pin from the $\overline{ALM}$. Care must be exercised in attempting this as continued thermal overstress may reduced component life.
11	18	I_{LMT}	Loop Current Limit - Voltage on this pin sets the short loop current limiting conditions using a resistive voltage divider.
12	19	OUT1	The analog output of the spare operational amplifier.
13	20	-IN1	The inverting analog input of the spare operational amplifier.
14	22	TIP	An analog input connected to the TIP (more positive) side of the subscriber loop through a feed resistor and ring relay contact. Functions with the RING terminal to receive voice signals from the telephone and for loop monitoring purpose.
15	24	RING	An analog input connected to the RING (more negative) side of the subscriber loop through a feed resistor. Functions with the TIP terminal to receive voice signals from the telephone and for loop monitoring purposes.
16	25	RFS	Ring Feed Sense - Senses RING side of the loop for Ground Key Detection. During Ring injected ringing the ring signal at this node is isolated from RF via the ring relay. For Tip injected ringing, the RF and RFS pins must be shorted.
17	27	VRX	Receive Input, 4-Wire Side - A high impedance analog input. AC signals appearing at this input drive the Tip Feed and Ring Feed amplifiers differentially.
18	31	C_2	Capacitor #C_2 - An external capacitor to be connected between this terminal and ground. It prevents false ring trip detection from occurring when longitudinal currents are induced onto the subscriber loop from power lines and other noise sources. This capacitor should be nonpolarized.

Pin Descriptions (Continued)

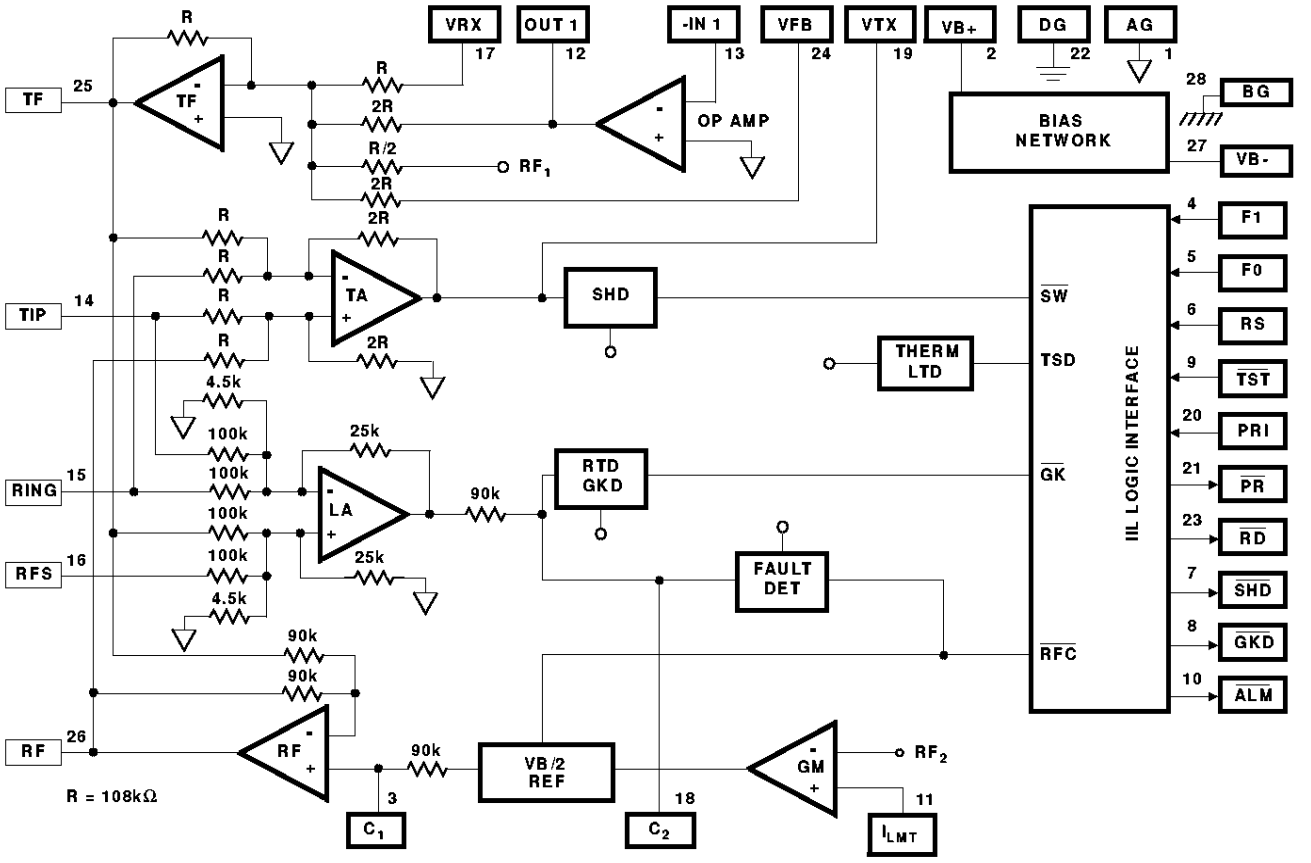
DIP/SOIC	PLCC	SYMBOL	DESCRIPTION
19	32	VTX	Transmit Output, 4-Wire Side - A low impedance analog output which represents the differential voltage across TIP and RING. Transhybrid balancing must be performed beyond this output to completely implement 2-Wire to 4-Wire conversion. This output is referenced to analog ground. Since the DC level of this output varies with loop current, capacitive coupling to the next stage is necessary.
20	33	PRI	A TTL compatible input used to control $\overline{PR}$. PRI active High = $\overline{PR}$ active low.
21	34	$\overline{PR}$	An active low open collector output. Can be used to drive a Polarity Reversal Relay.
22	35	DG	Digital Ground - To be connected to zero potential. Serves as a reference for all digital inputs and outputs on the SLIC.
23	36	$\overline{RD}$	Ring Relay Driver - An active low open collector output. Used to drive a relay that switches ringing signals onto the 2-Wire line.
24	37	VFB	Feedback input to the tip feed amplifier; may be used in conjunction with transmit output signal and the spare op amp to accommodate 2-Wire line impedance matching.
25	38	TF_2	Tip Feed - A low impedance analog output connected to the TIP terminal through a feed resistor. Functions with the RF terminal to provide loop current, and to feed voice signals to the telephone set and to sink longitudinal currents. Must be tied to TF_1.
NA	39	TF_1	Tie directly to TF_2 in the PLCC application.
26	41	RF_1	Ring Feed - A low impedance analog output connected to the RING terminal through a feed resistor. Functions with the TF terminal to provide loop current, feed voice signals to the telephone set, and to sink longitudinal currents. Tie directly to RF_2.
NA	42	RF_2	Tie directly to RF_1 in the PLCC application.
27	43	VB-	The battery voltage source. The most negative supply.
28	44	BG	Battery Ground - To be connected to zero potential. All loop current and some quiescent current flows into this ground terminal.
	1, 5, 6, 7, 14, 15, 16, 21, 23, 26, 28, 29, 30, 40	NC	No internal connection.

NOTE:

1. All grounds (AG, BG, DG) must be applied before V_{B+} or V_{B-}. Failure to do so may result in premature failure of the part. If a user wishes to run separate grounds off a line card, the AG must be applied first.

Functional Diagram

DIP OR SOIC



Die Characteristics

Transistor Count 224
Diode Count 28
Die Dimensions . . . . . .174 x 120
Substrate Potential . . . . . .Connected
Process. . . . . Bipolar-DI

Overvoltage Protection and Longitudinal Current Protection

The SLIC device, in conjunction with an external protection bridge, will withstand high voltage lightning surges and power line crosses.

High voltage surge conditions are as specified in Table 1.

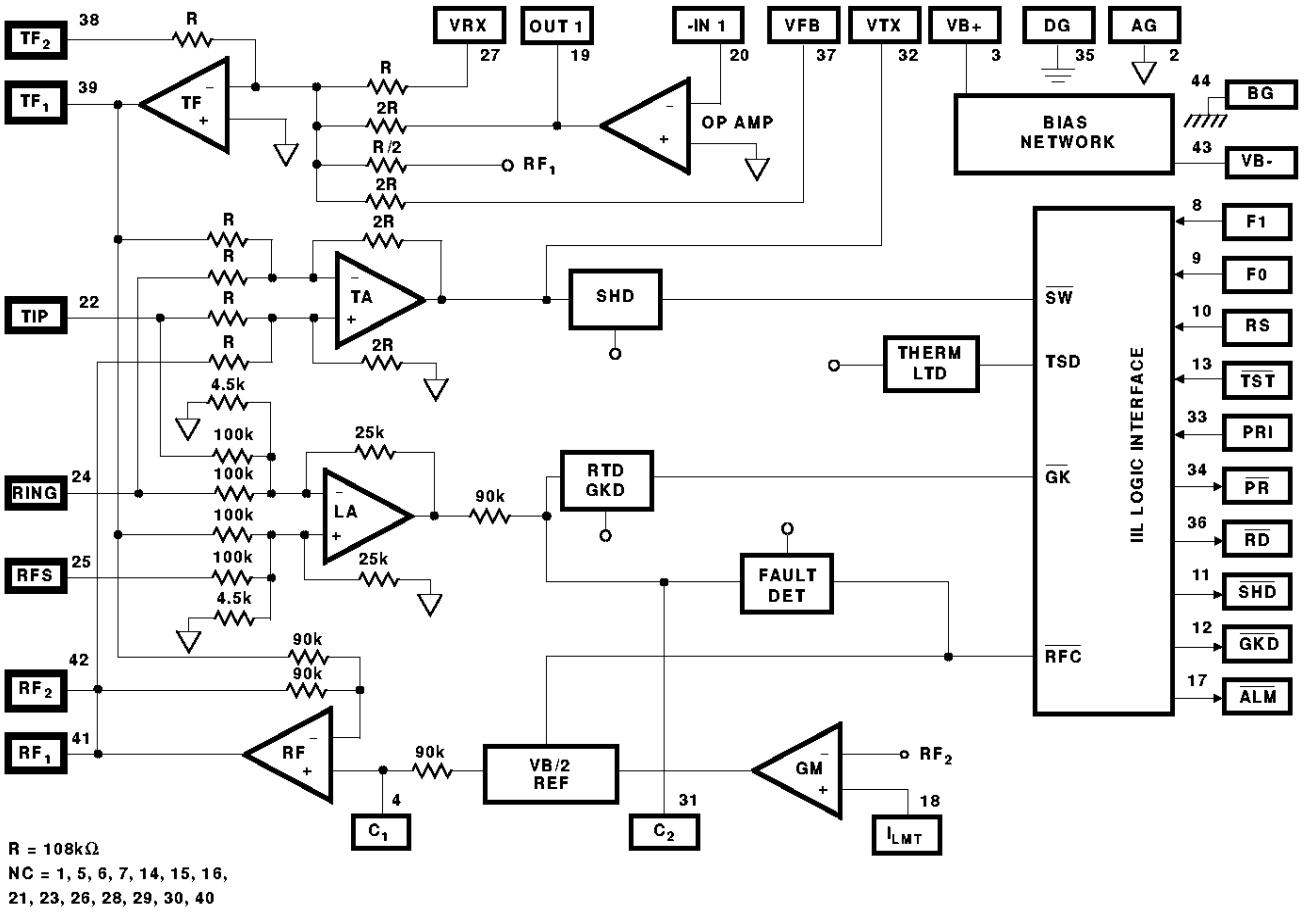
The SLIC will withstand longitudinal currents up to a maximum or $30mA_{RMS}$, $15mA_{RMS}$ per leg, without any performance degradation.

TABLE 1.

PARAMETER	TEST CONDITION	PERFORMANCE (MAX)	UNITS
Longitudinal Surge	10µs Rise/ 1000µs Fall	±1000 (Plastic)	V_{PEAK}
		±500 (Ceramic)	V_{PEAK}
Metallic Surge	10µs Rise/ 1000µs Fall	±1000 (Plastic)	V_{PEAK}
		±500 (Ceramic)	V_{PEAK}
T/GND R/GND	10µs Rise/ 1000µs Fall	±1000 (Plastic)	V_{PEAK}
		±500 (Ceramic)	V_{PEAK}
50/60Hz Current			
T/GND	11 Cycles	700 (Plastic)	V_{RMS}
R/GND	Limited to $10A_{RMS}$	350 (Ceramic)	V_{RMS}

Functional Diagram (Continued)

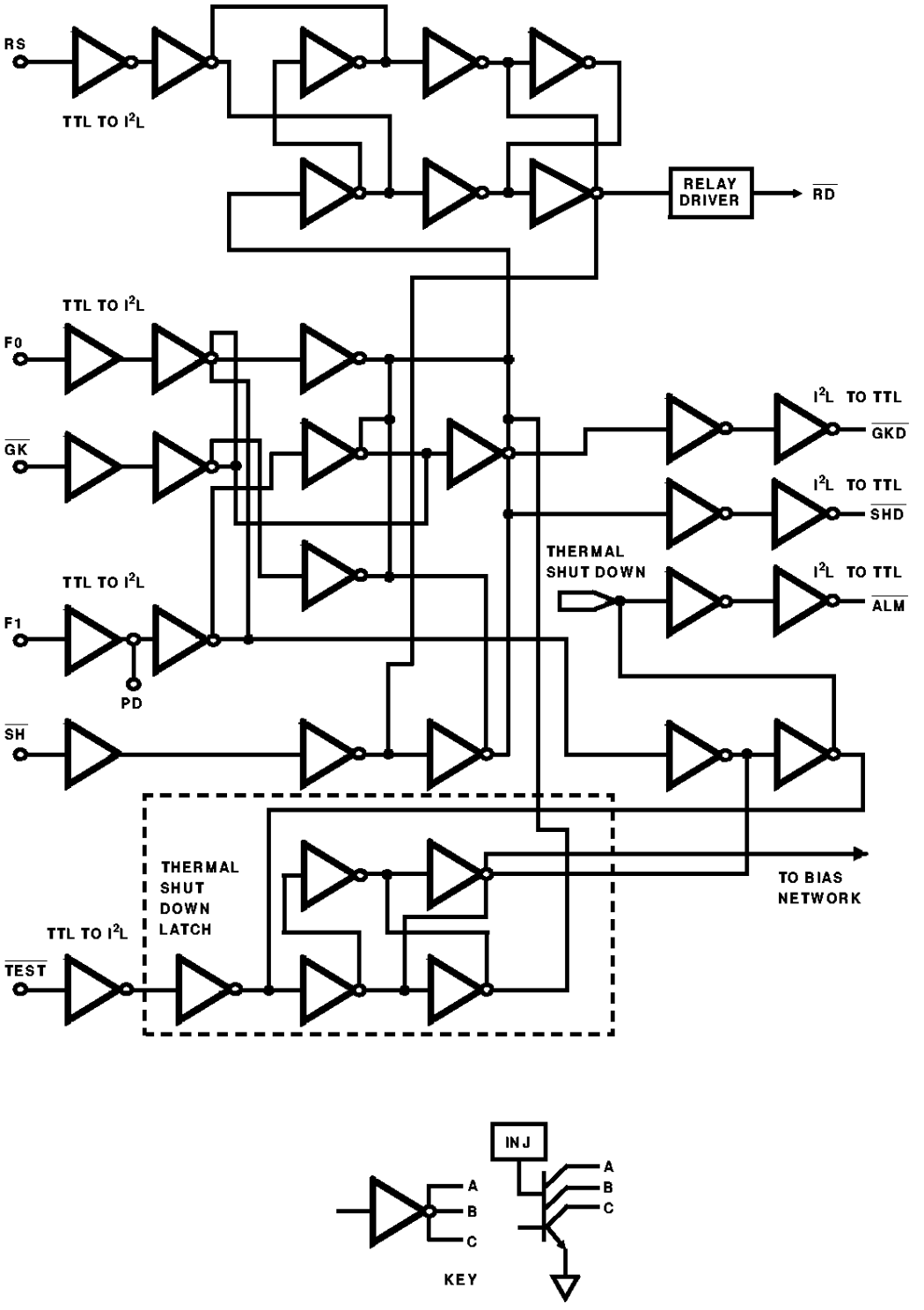
PLCC



R = 108kΩ

NC = 1, 5, 6, 7, 14, 15, 16, 21, 23, 26, 28, 29, 30, 40

Logic Diagram



Applications Diagram

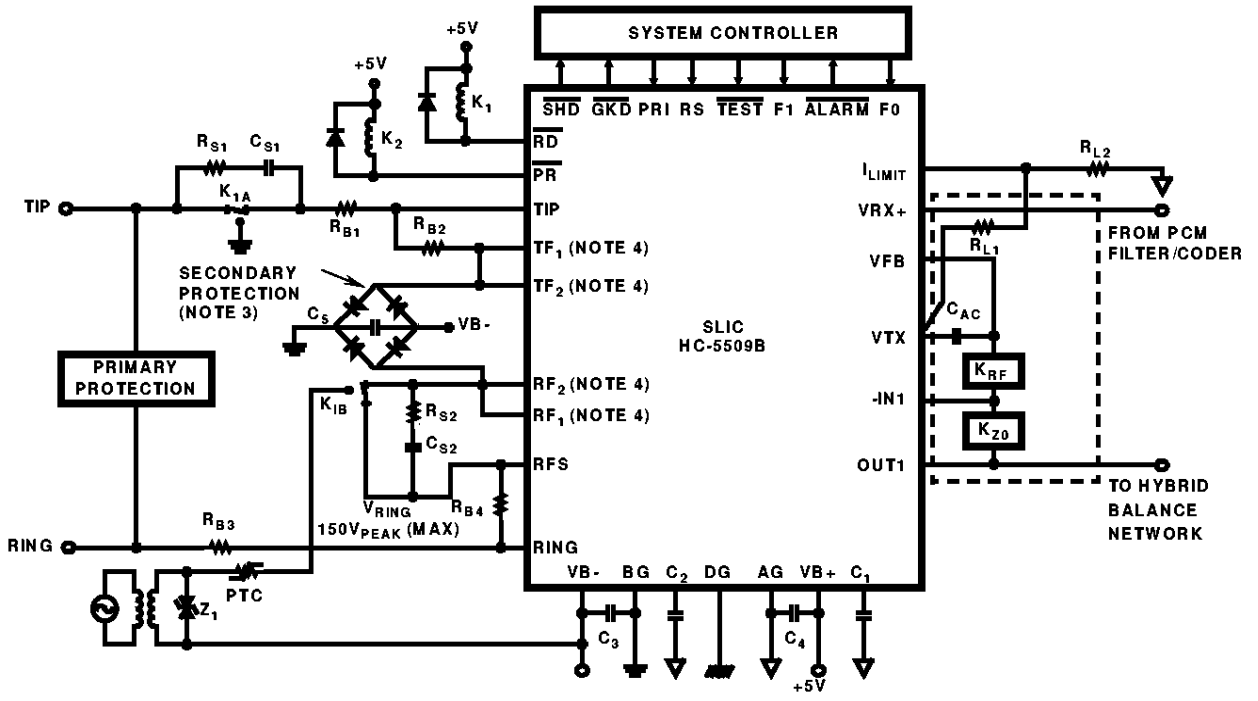


FIGURE 1. TYPICAL LINE CIRCUIT APPLICATION WITH THE MONOLITHIC SLIC

TYPICAL COMPONENT VALUES

C_1 = 0.5µF, 30V

C_2 = 0.5µF-1.0µF ±10%, 20V (Should be nonpolarized)

C_3 = 0.01µF, 100V, ±20%

C_4 = 0.01µF, 100V, ±20%

C_5 = 0.01µF, 100V, ±20%

C_{AC} = 0.5µF, 20V

KZ_0 = 60kΩ, (Z_0 = 600Ω, K = Scaling Factor = 100)

R_{L1}, R_{L2}; Current Limit Setting Resistors:

$R_{L1} + R_{L2} > 90k\Omega \rightarrow$ offset

$I_{LIMIT} = (0.6)\ (R_{L1} + R_{L2})/(200 \times R_{L2})$, R_{L1} typically 100kΩ

K_{RF} = 20kΩ, RF = 2(R_{B2} + R_{B4}), K = Scaling Factor = 100)

$R_{B1} = R_{B2} = R_{B3} = R_{B4}$ = 50Ω (1% absolute, matching requirements covered in a Tech Brief)

$R_{S1} = R_{S2}$ = 1kΩ typically

$C_{S1} = C_{S2}$ = 0.1µF, 200V typically, depending on V_{Ring} and line length.

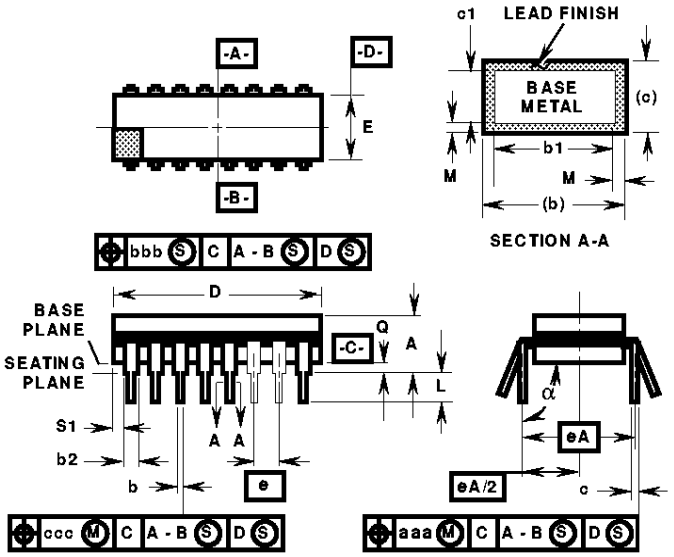
Z_1 = 150V to 200V transient protector. PTC used as ring generator ballast.

NOTES:

1. All grounds (AG, BG, & DG) must be applied before V_B+ or V_B-. Failure to do so may result in premature failure of the part. If a user wishes to run separate grounds off a line card, the AG must be applied first.
2. Application shows Ring Injected Ringing, a Balanced or Tip injected configuration may be used.
3. Secondary protection diode bridge recommended is 3A, 200V type.
4. TF_1, TF_2 and RF_1, RF_2 are on PLCC only and should be connected together as shown.

Additional information is contained in Application Note 549, "The HC-550X Telephone SLICs" By Geoff Phillips

Ceramic Dual-In-Line Frit Seal Packages (CerDIP)



F28.6 MIL-STD-1835 GDIP1-T28 (D-10, CONFIGURATION A)
28 LEAD CERAMIC DUAL-IN-LINE FRIT SEAL PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.232	-	5.92	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
c	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	1.490	-	37.85	5
E	0.500	0.610	12.70	15.49	5
e	0.100 BSC		2.54 BSC		-
eA	0.600 BSC		15.24 BSC		-
eA/2	0.300 BSC		7.62 BSC		-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
α	90°	105°	90°	105°	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
ccc	-	0.010	-	0.25	-
M	-	0.0015	-	0.038	2, 3
N	28		28		8

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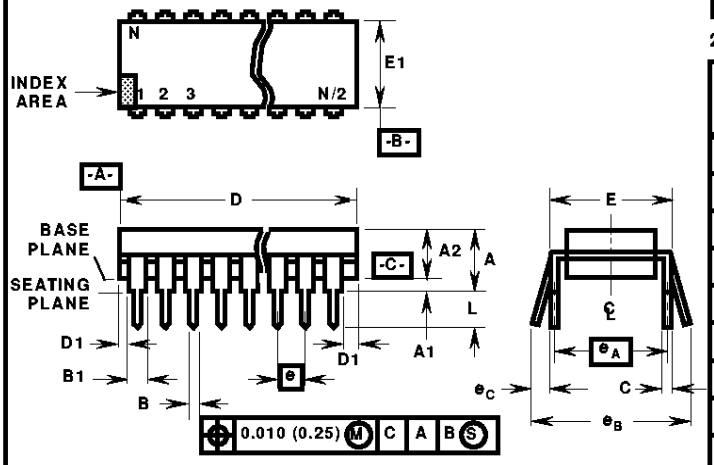
NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
4. Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
5. This dimension allows for off-center lid, meniscus, and glass overrun.
6. Dimension Q shall be measured from the seating plane to the base plane.
7. Measure dimension S1 at all four corners.
8. N is the maximum number of terminal positions.
9. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
10. Controlling dimension: INCH.

Dual-In-Line Plastic Packages (PDIP)



NOTES:

1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and e_A are measured with the leads constrained to be perpendicular to datum -C-.
7. e_B and e_C are measured at the lead tips with the leads unconstrained. e_C must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E28.6 (JEDEC MS-011-AB ISSUE B)
28 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.250	-	6.35	4
A1	0.015	-	0.39	-	4
A2	0.125	0.195	3.18	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.030	0.070	0.77	1.77	8
C	0.008	0.015	0.204	0.381	-
D	1.380	1.565	35.1	39.7	5
D1	0.005	-	0.13	-	5
E	0.600	0.625	15.24	15.87	6
E1	0.485	0.580	12.32	14.73	5
e	0.100 BSC		2.54 BSC		-
e_A	0.600 BSC		15.24 BSC		6
e_B	-	0.700	-	17.78	7
L	0.115	0.200	2.93	5.08	4
N	28		28		9

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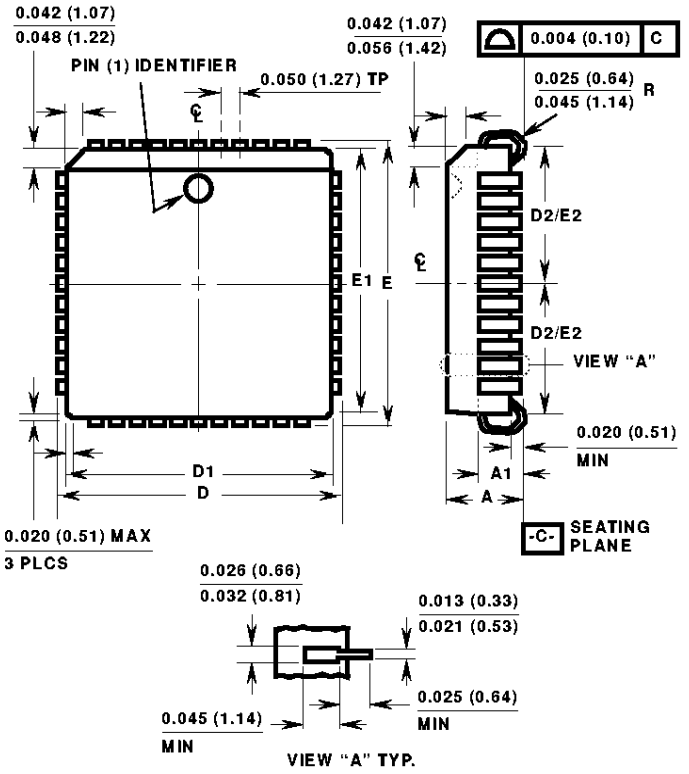
Plastic Leaded Chip Carrier Packages (PLCC)



N44.65 (JEDEC MS-018AC ISSUE A)
44 LEAD PLASTIC LEADED CHIP CARRIER PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.165	0.180	4.20	4.57	-
A1	0.090	0.120	2.29	3.04	-
D	0.685	0.695	17.40	17.65	-
D1	0.650	0.656	16.51	16.66	3
D2	0.291	0.319	7.40	8.10	4, 5
E	0.685	0.695	17.40	17.65	-
E1	0.650	0.656	16.51	16.66	3
E2	0.291	0.319	7.40	8.10	4, 5
N	44		44		6

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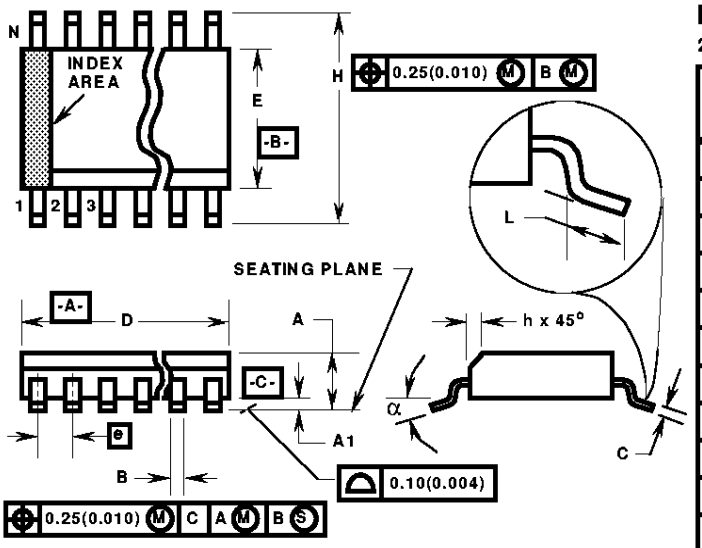
NOTES:

1. Controlling dimension: INCH. Converted millimeter dimensions are not necessarily exact.
2. Dimensions and tolerancing per ANSI Y14.5M-1982.
3. Dimensions D1 and E1 do not include mold protrusions. Allowable mold protrusion is 0.010 inch (0.25mm) per side.
4. To be measured at seating plane -C- contact point.
5. Centerline to be determined where center leads exit plastic body.
6. "N" is the number of terminal positions.

Small Outline Plastic Packages (SOIC)



M28.3 (JEDEC MS-013-AE ISSUE C)
28 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0926	0.1043	2.35	2.65	-
A1	0.0040	0.0118	0.10	0.30	-
B	0.013	0.0200	0.33	0.51	9
C	0.0091	0.0125	0.23	0.32	-
D	0.6969	0.7125	17.70	18.10	3
E	0.2914	0.2992	7.40	7.60	4
e	0.05 BSC		1.27 BSC		-
H	0.394	0.419	10.00	10.65	-
h	0.01	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	28		28		7
α	0^o	8^o	0^o	8^o	-

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NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

All Harris Semiconductor products are manufactured, assembled and tested under **ISO9000** quality systems certification.

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